

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier | | User Part Number | | | | | | |
|--|--|--|-----------------------------------|-----------|------------|-----------|--|--|
| Nexperia B.V. Name of Laboratory Assembly reliability labs | | PMEG2030CER | | | | | | |
| | | Part Description | | | | | | |
| | | Nexperia DHAM | Schottky | | | | | |
| | | SMD package | | | | | | |
| Test | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST Pre- and Post-Stress | | | | | | | |
| # 1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| # 2 | PC Preconditioning | JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering | 24 hours 168 hours 3 cycles | 1514 | 64430 | 0 | | |
| # 5 | HTRB High Temperature Reverse Bias | MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage ^[1] | 1000 hours | 206 | 9320 | 0 | | |
| # 7 | TC Temperature Cycling | JESD22-A104 -65 °C to Tjmax, not to exceed 150°C | 500 cycles | 311 | 14080 | 0 | | |
| # 8 or | UHAST Unbiased HAST | JESD22-A118 Tamb = 130 °C, RH = 85 % | – 96 hours | 311 | 14080 | 0 | | |
| # 8a | AC Autoclave | JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia) | _ 50 Hours | | | | | |
| # 9 | H3TRB High Humidity High Temperature Reverse Bias | JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage $^{[1],[2]}$ | 1000 hours | 311 | 14080 | 0 | | |
| # 10 | IOL Intermittent Operating Life | MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C | 333 hours | 312 | 14120 | 0 | | |
| # 20 | RSH Resistance to Solder Heat | JESD22-A111 260 °C ± 5 °C | 10 s | 269 | 8070 | 0 | | |
| # 21 | SD Solderability | J-STD-002 | | 222 | 6660 | 0 | | |

^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM | Schottky | 9320 | 0 | 0,46 | 2,19E+09 |

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^[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.